

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Ting-Yao Lin	08/23/2017
Kun-Hsien Lee	08/17/2017
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<b>Name:</b>	UNITED MICROELECTRONICS CORP.
<b>Street Address:</b>	No.3, Li-Hsin Road 2, Science-Based Industrial Park
<b>City:</b>	Hsin-Chu City
<b>State/Country:</b>	TAIWAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14990806
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	NAUP2660USA
<b>NAME OF SUBMITTER:</b>	SIBYL YU
<b>SIGNATURE:</b>	/SIBYL YU/
<b>DATE SIGNED:</b>	09/06/2017
<b>Total Attachments: 4</b> source=NP005#page1.tif source=NP005#page2.tif source=NP005#page3.tif source=NP005#page4.tif	

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

**Title of Invention:**

**METHOD OF FORMING SEMICONDUCTOR DEVICE**

As the below named inventor, I hereby declare that:  
This declaration is directed to:

☐ The attached application, or

☒ United States application number 14/990,806 filed on 01/08/2016, or

☐ PCT international application number \_\_\_\_\_ filed on \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by **UNITED MICROELECTRONICS** having a postal address of **CORP.**

**No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.**

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this AUG 23 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP2660USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Ting-Yao Lin**

Date: **AUG 23 2017**

Signature: Ting-Yao Lin

NPO#NAU-P2660-USA:0  
CUST#UMCD-2015-0674

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F#NPO-P0002E-US1201  
DSB0-106U016760

**PATENT**  
**REEL: 043492 FRAME: 0895**

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

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representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said legal equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this AUG 17 2017 (Date of signing)

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No NAUP2660USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Kun-Hsien Lee**

Date: **AUG 17 2017**

Signature:

Kun Hsien Lee

NPO#NAU-P2660-USA:0  
CUST#UMCD-2015-0674

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RECORDED: 09/06/2017

**PATENT**  
**REEL: 043492 FRAME: 0897**